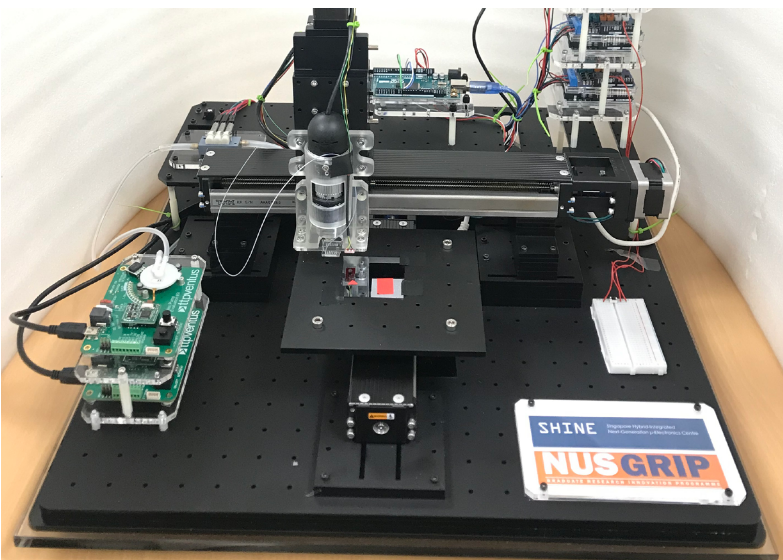
2D/3D Heterogeneous Integration - Next Generation of Micro-transfer Technology

Technology advancement pushes semiconductor dies to be smaller, thinner, more fragile, and more compact. Conventional vacuum-based pick and place systems are only suitable for rigid components with large dimensions (>100 μm) and homogeneous materials. The first generation of micro-transfer printing (MTP) technology which is peeling rate-dependent can only circumvent a few issues from vacuum-based system. Hi-Transfer cover the gaps from the first generation of MTP and enables next generation of micro transfer technology for heterogeneous integration in semiconductor industry.



Dr Zhang Yu
Chief Technology Officer

Dr Xu Baochang
Chief Executive Officer

Professor Aaron Thean
Technical Advisor

Saw Biing Huei
Venture Architect

Peter Tan
Commercial Champion

Dr Lee Pui Mun
Technology Manager

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